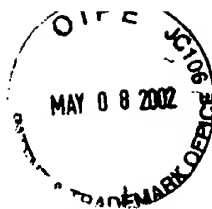


Attorney Docket No.: 042390.P8875



COPY OF PAPERS
ORIGINALLY FILED

PATENT RECEIVED

#8/ELE
5-21-2
Surles

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re application of:

Xiao-Chun Mu, et al.

Application No: 09/733,289

Filed: December 8, 2000

For: MICROELECTRONIC PACKAGE HAVING
AN INTEGRATED HEAT SINK AND
BUILD-UP LAYERS

TC 2800 MAIL ROOM

Examiner: D. Nguyen

Art Unit: 2814

I hereby certify that this correspondence is being deposited with the United States Postal Service as first class mail with sufficient postage in an envelope addressed to the Commissioner of Patents, Washington, D.C. 20231 on:

26 APRIL 2002
Date of Deposit

DEBORAH L. HIGHAM
Name of Person Mailing Correspondence

Deborah O. Higham
Signature Date 4/26/02

Box Non-Fee Amendment

Assistant Commissioner For Patents
Washington, D.C. 20231

AMENDMENT

Dear Sir:

In response to the Office Action mailed April 11, 2002, Applicants elect Claim

Set I, as set forth in the April 11, 2002 Office Action, which includes claims 1-5 and

10-17 without traverse. Applicants elect the species of Embodiment 5, as set forth in the

April 11, 2002 Office Action, which includes figures 20-26. Please charge any shortages

and credit any overcharges to our Deposit Account number 02-2666.

Respectfully submitted,
BLAKELY, SOKOLOFF, TAYLOR & ZAFMAN, LLP

Date:

APRIL 26, 2002

Paul A. Mendonsa
Reg. No. 42,879

12400 Wilshire Boulevard
Seventh Floor
Los Angeles, CA 90025-1026
(503) 684-6200